



## Main Features

- 2nd Generation Intel® Core™ Mobile Processors
- Intel® QM67/HM65 PCH
- 1x DDR3 SO-DIMM socket support non-ECC DDR3 800/1066/1333MHz up to 8GB
- Type 2 COM Express Module Support 6 Express Lanes, 32 bit PCI Interface, One IDE and Gigabit LAN

## Product Overview

The ICES 267 is a COM Express Type 2 basic module featuring Intel® QM67/HM65 Platform Control Hub, which supports 2nd generation Intel® Core™ Mobile processors and one DDR3 SO-DIMM memory socket up to 8GB. The ICES 267 integrated with Intel® HD graphics or expands via PCI Express Graphic 1x 16 lane to carrier board; it also supports other display types include LFP or Dual channel LVDS. The high performance ICES 267 COM Express Module supports 4x SATA, 8x USB2.0 and 6X PCIe x1 lanes through the carrier board. It is compatible with ICEB 8050 carrier board and in-house designed ICES 267 F-kits from NEXCOM.

## Specifications

### CPU Support

- Support 2nd generation Intel® Core™ processor family, rPGA 988

Processor	i5-2510E	i3-2330E	Celeron® B810
# of Core	2	2	2
Clock Speed	2.5GHz	2.2GHz	1.6GHz
Max. TDP	35W	35W	35W

### Main Memory

- One DDR3 1066/1333 MHz SO-DIMM, up to 8GB

### Platform Control Hub

- QM67/ HM65

### BIOS

- AMI System BIOS
- Plug and play support

### Display

- Intel® HD graphics solution
- One PCI Express X 16 Lane down to the carried board
- Drive a standard progressive scan analog monitor with resolution up to 2048 x 1536 @ 60Hz
- Supports LVDS 18/24-bit & single/dual channel interface

### Audio

- HD audio interface

### On-board LAN

- Intel® 82579LM Gigabit Ethernet, support iAMT 7.0 (supported with QM67 only)
- Support boot from LAN, wake on LAN function
- Signals down to I/O board

### COM Express Connector

- AB  
VGA/ LVDS/ 8x USB 2.0/ HD Audio/ 3x SATA/ LAN/ GPIO/ LPC bus  
One PCIe X4/ two PCIe X1/ SMBus (I2C)/ SPI BIOS
- CD  
PCIe x16/ IDE/ PCI

### Power Requirements

- +12V, +5VSB, +3.3V RTC power

### Dimensions

- 95mm (W) x 125mm (L)

